

CIRCUIT PACKAGE AND METHOD OF PLATING THE SAME

Abstract of the Disclosure

A circuit package includes a base portion and a first metal pattern
5 disposed on a substrate surface. Second and third metal patterns are disposed
on another substrate surface, and electrically coupled to first and second vias.
The third metal pattern forms a gap to electrically isolate it from the second
metal pattern. A circuit package includes a substrate having an opening and a
single heat sink positioned in the opening to expose top and bottom surfaces
10 through top and bottom surfaces of the substrate. Selective plating includes
applying first and second metal patterns to a substrate surface, creating a
potential voltage difference between the first metal pattern and a metal source,
and plating the first metal pattern by attracting a first metal type to the voltage
potential of the first metal pattern. The voltage potential of the first metal
15 pattern is less than the voltage potential of the metal source.